

FEATURES

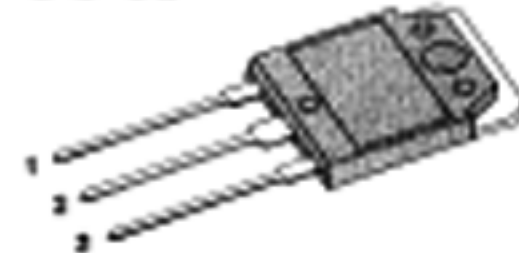
- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- Lower Leakage Current : 25 μ A (Max.) @ $V_{DS} = 700V$
- Low $R_{DS(on)}$: 1.552 Ω (Typ.)

$$BV_{DSS} = 700 V$$

$$R_{DS(on)} = 1.8 \Omega$$

$$I_D = 6 A$$

TO-3P



1. Gate 2. Drain 3. Source

Absolute Maximum Ratings

| Symbol | Characteristic | Value | Units |
|----------------|---|--------------|------------|
| V_{DSS} | Drain-to-Source Voltage | 700 | V |
| I_D | Continuous Drain Current ($T_C=25^\circ C$) | 6 | A |
| | Continuous Drain Current ($T_C=100^\circ C$) | 3.8 | |
| I_{DM} | Drain Current-Pulsed ③ | 24 | A |
| V_{GS} | Gate-to-Source Voltage | ± 30 | V |
| E_{AS} | Single Pulsed Avalanche Energy ② | 582 | mJ |
| I_{AR} | Avalanche Current ③ | 6 | A |
| E_{AR} | Repetitive Avalanche Energy ③ | 14 | mJ |
| dv/dt | Peak Diode Recovery dv/dt ③ | 2.5 | V/ns |
| P_D | Total Power Dissipation ($T_C=25^\circ C$) | 140 | W |
| | Linear Derating Factor | 1.12 | |
| T_J, T_{STG} | Operating Junction and Storage Temperature Range | - 55 to +150 | $^\circ C$ |
| T_L | Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5-seconds | 300 | |

Thermal Resistance

| Symbol | Characteristic | Typ. | Max. | Units |
|-----------------|---------------------|------|------|--------------|
| $R_{\theta JC}$ | Junction-to-Case | -- | 0.89 | $^\circ C/W$ |
| $R_{\theta CS}$ | Case-to-Sink | 0.24 | -- | |
| $R_{\theta JA}$ | Junction-to-Ambient | -- | 40 | |

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

| Symbol | Characteristic | Min. | Typ. | Max. | Units | Test Condition |
|------------------------|---|------|------|------|----------|--|
| BV_{DSS} | Drain-Source Breakdown Voltage | 700 | — | — | V | $V_{GS}=0V, I_D=250\mu A$ |
| $\Delta BV/\Delta T_J$ | Breakdown Voltage Temp. Coeff. | — | 0.79 | — | V/°C | $I_D=250\mu A$ See Fig 7 |
| $V_{GS(th)}$ | Gate Threshold Voltage | 2.0 | — | 4.0 | V | $V_{DS}=5V, I_D=250\mu A$ |
| I_{GSS} | Gate-Source Leakage, Forward | — | — | 100 | nA | $V_{GS}=30V$ |
| | Gate-Source Leakage, Reverse | — | — | -100 | | $V_{GS}=-30V$ |
| I_{DSS} | Drain-to-Source Leakage Current | — | — | 25 | μA | $V_{DS}=700V$ |
| | | — | — | 250 | | $V_{DS}=560V, T_C=125^\circ\text{C}$ |
| $R_{DS(on)}$ | Static Drain-Source On-State Resistance | — | — | 1.8 | Ω | $V_{GS}=10V, I_D=3A$ ④ |
| g_{fs} | Forward Transconductance | — | 4.12 | — | Ω | $V_{DS}=50V, I_D=3A$ ⑤ |
| C_{iss} | Input Capacitance | — | 920 | 1200 | pF | $V_{GS}=0V, V_{DS}=25V, f=1\text{MHz}$ See Fig 5 |
| C_{oss} | Output Capacitance | — | 100 | 115 | | |
| C_{rss} | Reverse Transfer Capacitance | — | 45 | 55 | | |
| $t_{d(on)}$ | Turn-On Delay Time | — | 18 | 45 | ns | $V_{DS}=350V, I_D=6A,$ $R_G=11.5$ See Fig 13 ④ ⑤ |
| t_r | Rise Time | — | 23 | 55 | | |
| $t_{d(off)}$ | Turn-Off Delay Time | — | 76 | 160 | | |
| t_f | Fall Time | — | 26 | 60 | | |
| Q_g | Total Gate Charge | — | 51 | 67 | nC | $V_{DS}=560V, V_{GS}=10V,$ $I_D=6A$ See Fig 6 & Fig 12 ④ ⑤ |
| Q_{gs} | Gate-Source Charge | — | 8.3 | — | | |
| Q_{gd} | Gate-Drain("Miller") Charge | — | 23.1 | — | | |

Source-Drain Diode Ratings and Characteristics

| Symbol | Characteristic | Min. | Typ. | Max. | Units | Test Condition |
|----------|---------------------------|------|------|------|---------|---|
| I_S | Continuous Source Current | — | — | 6 | A | Integral reverse pn-diode in the MOSFET |
| I_{SM} | Pulsed-Source Current ① | — | — | 24 | | |
| V_{SD} | Diode Forward Voltage ④ | — | — | 1.4 | V | $T_J=25^\circ\text{C}, I_S=6A, V_{GS}=0V$ |
| t_{rr} | Reverse Recovery Time | — | 440 | — | ns | $T_J=25^\circ\text{C}, I_S=6A$ |
| Q_{rr} | Reverse Recovery Charge | — | 4.05 | — | μC | $di_F/dt=100A/\mu s$ ④ |

Notes :

① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature

② $L=30\text{mH}, I_{AS}=6A, V_{DS}=50V, R_G=27\Omega$, Starting $T_J=25^\circ\text{C}$ ③ $I_{SD}\leq 6A, di/dt\leq 140A/\mu s, V_{SD}\leq BV_{DSS}$, Starting $T_J=25^\circ\text{C}$ ④ Pulse Test : Pulse Width = 250 μs , Duty Cycle $\leq 2\%$

⑤ Essentially Independent of Operating Temperature

Fig 1. Output Characteristics

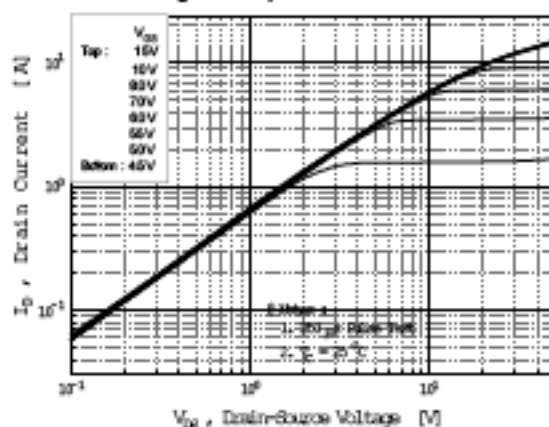


Fig 2. Transfer Characteristics

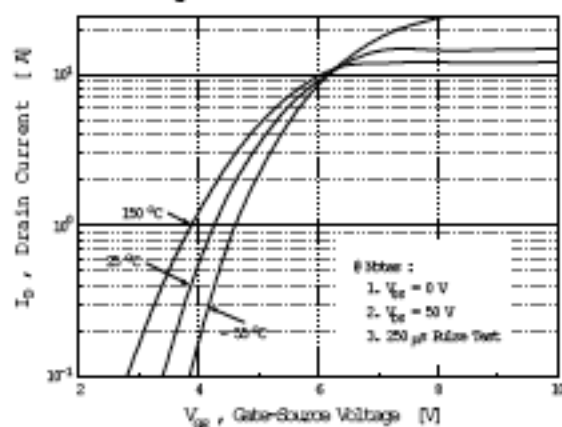


Fig 3. On-Resistance vs. Drain Current

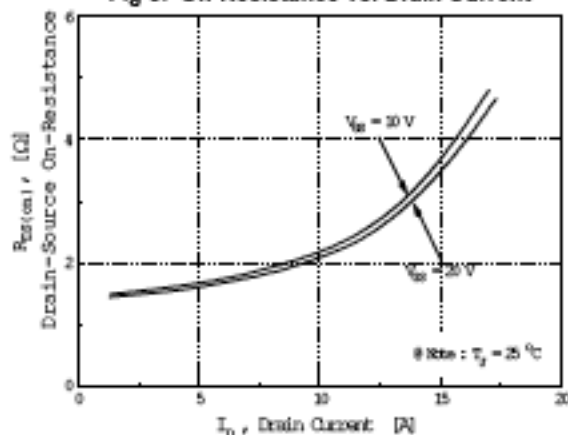


Fig 4. Source-Drain Diode Forward Voltage

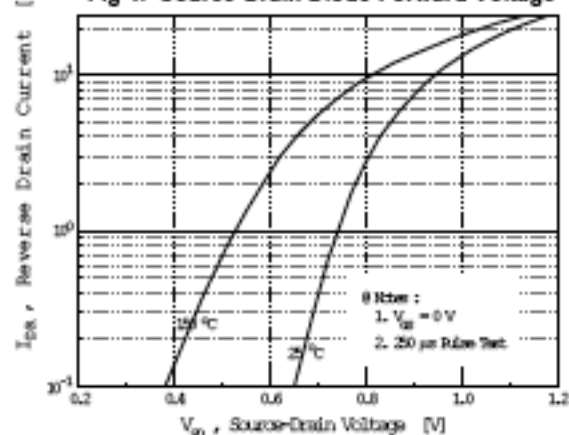


Fig 5. Capacitance vs. Drain-Source Voltage

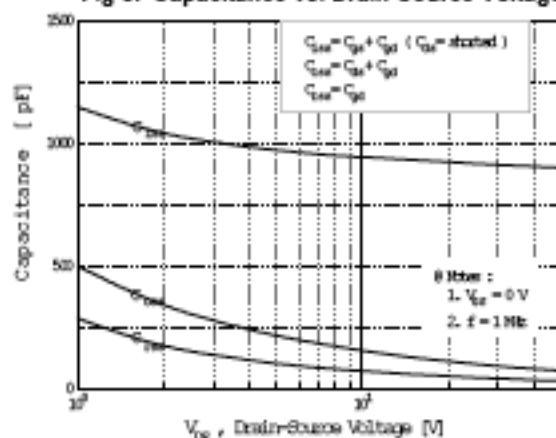
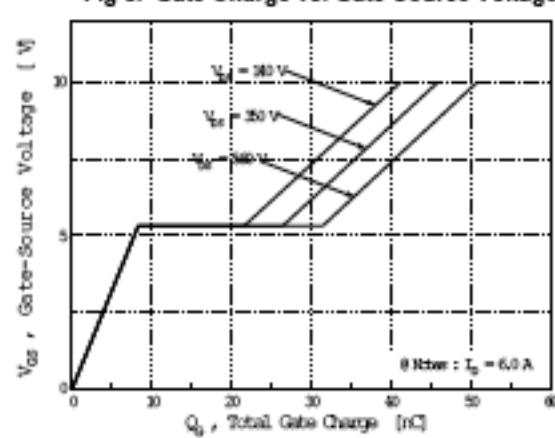


Fig 6. Gate Charge vs. Gate-Source Voltage



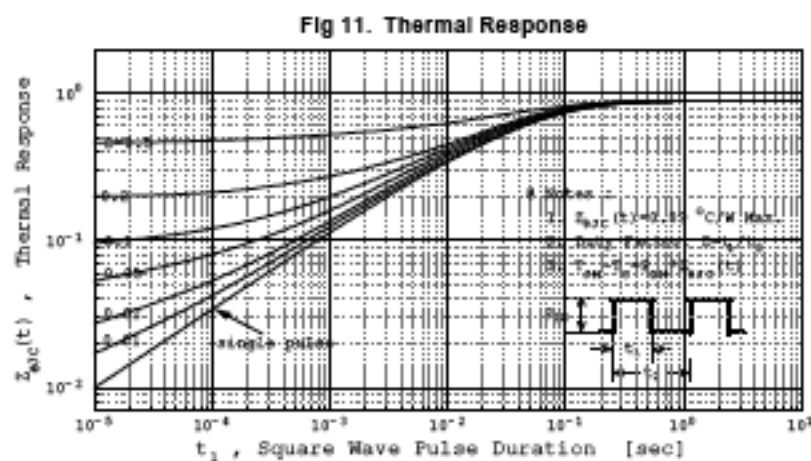
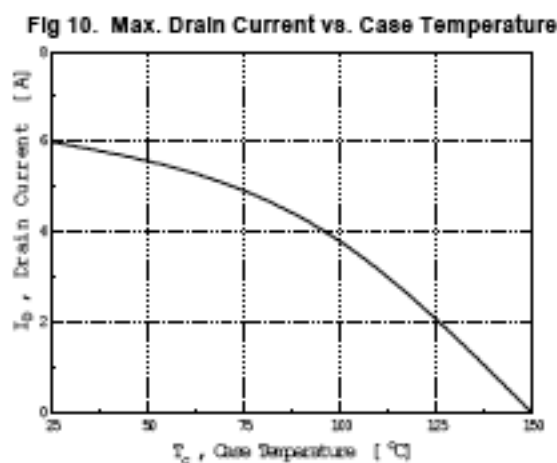
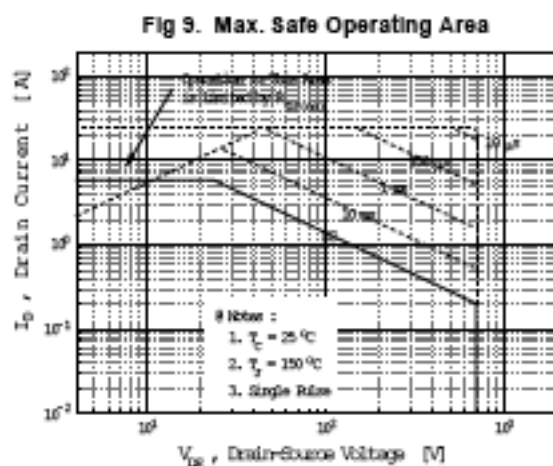
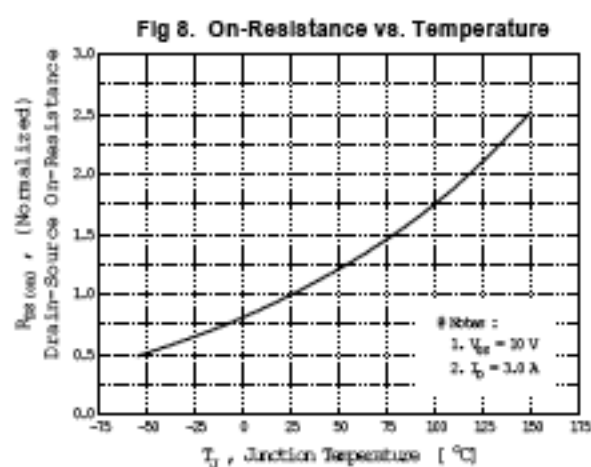
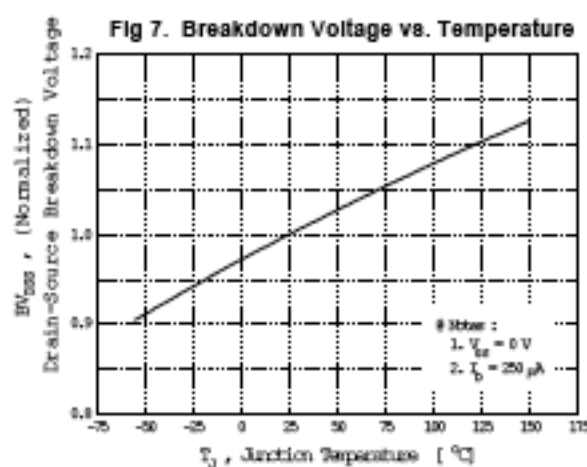


Fig 12. Gate Charge Test Circuit & Waveform

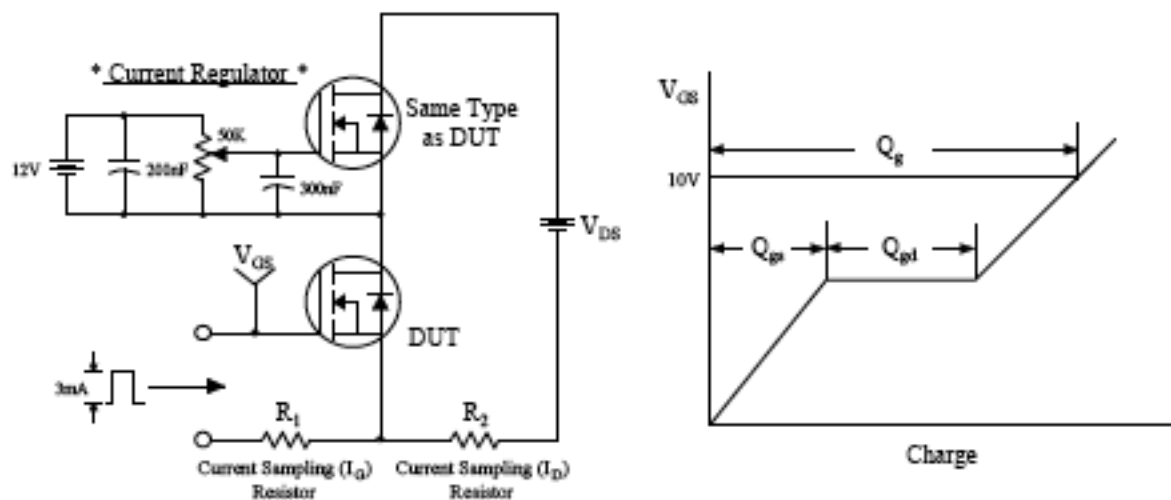


Fig 13. Resistive Switching Test Circuit & Waveforms

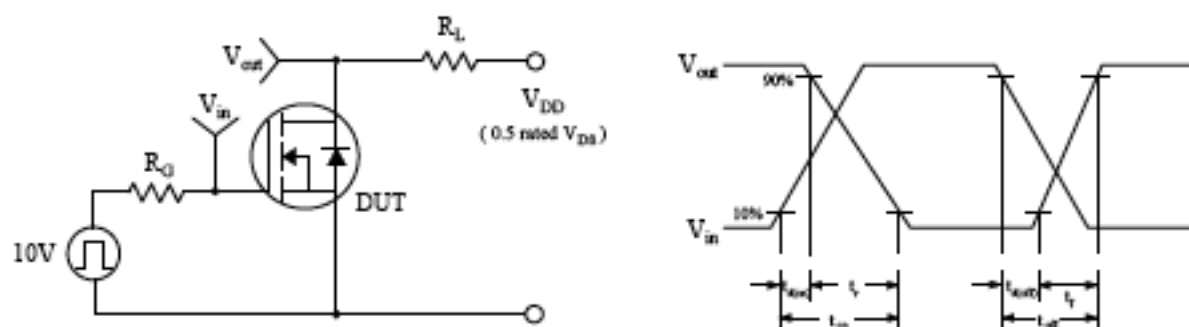


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

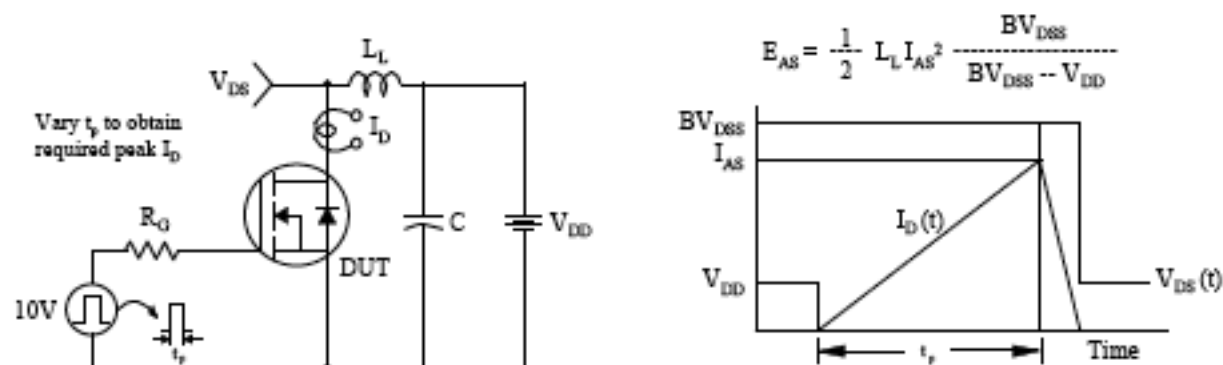
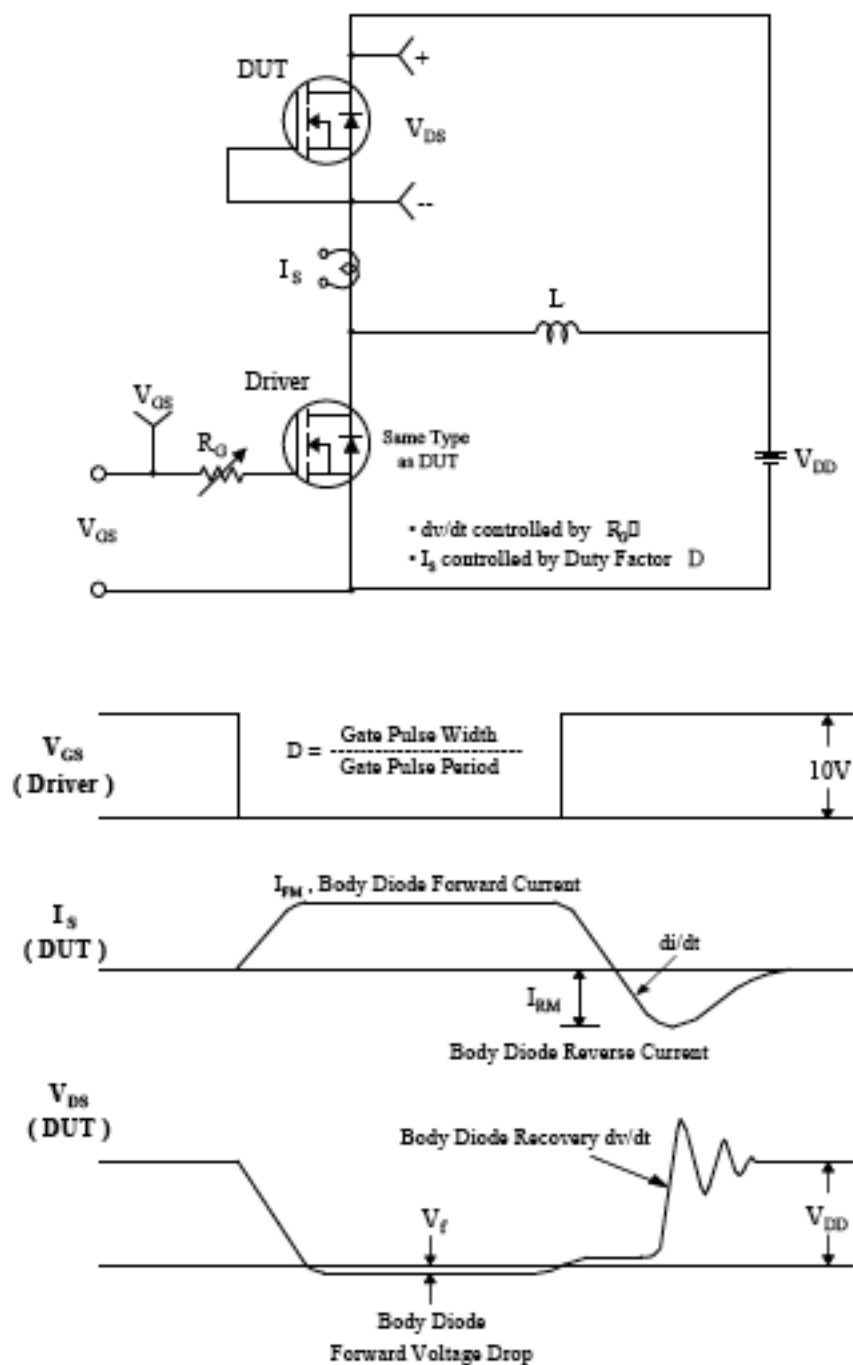


Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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